



TE Internal #: 2-1474654-1

Wire-to-Board, 22 Position, 2.54 mm [.1 in] Centerline, 50.8 mm [2 in] Length, Printed Circuit Board, Power & Signal, Wire-to-Board Jumpers & Shunts

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Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Jumpers & Shunts



Connector System: **Wire-to-Board**

Number of Positions: **22**

Centerline (Pitch): **2.54 mm [.1 in]**

Product Length: **50.8 mm [2 in]**

Connector & Contact Terminates To: **Printed Circuit Board**

Features

Body Features

Jumper Insulation Material	Nomex
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Electrical Characteristics

Operating Voltage	300 VAC
Impedance	117 Ω

Contact Features

Pin Arrangement (Right)	A
Pin Arrangement (Left)	A
Contact Current Rating (Max)	3 A

Dimensions

Wire Size	24 AWG
Product Length	50.8 mm[2 in]

Configuration Features

Number of Conductors	22
Number of Rows	1
Number of Positions	22

Product Type Features

Compatible With Discrete Wire Type	Solid
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Connector System	Wire-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Housing Features

Centerline (Pitch)	2.54 mm [.1 in]
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Usage Conditions

Operating Temperature Range	-40 – 125 °C [-40 – 257 °F]
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Operation/Application

Circuit Application	Power & Signal
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Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the

product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Compatible Parts



Customers Also Bought





Documents

Product Drawings

[FSN-22A-22](#)

English

Product Specifications

[Product Specification](#)

English

Agency Approvals

[UL Report](#)

English